Panasonic

Zener Diode DZ2S030×0L

DZ2S030×0L Silicon epitaxial planar type

For constant voltage / For surge absorption circuit DZ2J030 in SSMini2 type package

Features

- · Excellent rising characteristics of zener current Iz
- Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: 3J or 3U

Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

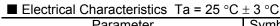
■ Absolute Maximum Ratings Ta = 25	Absolute Maximum Ratings Ta = 25 °C					
Parameter	Symbol	Rating	Unit			
Repetitive peak forward current	IFRM	200	mA mW kV °C °C			
Total power dissipation *1	PT	200 m 150 m ¹ ±15 k ¹ 150 °(-40 to +85 °(mW			
Electrostatic discharge *2	ESD	±15	kV			
Junction temperature	Tj	150	°C			
Operating ambient temperature	Topr	-40 to +85	°C			
Storage temperature	Teta	-55 to +150	ŝ			

 Storage temperature
 Tstg
 -55
 to
 +150
 °C

 Note)
 *1
 Mounted on glass epoxy print board (45 mm × 45 mm × 1 mm)
 Solder in (0.8 mm × 0.6 mm)

*2 Test method : IEC61000_4_2

(C = 150 pF, R = 330 Ω , Contact discharge : 10 times)



Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage ^{*1, *2}	VZ	IZ = 5 mA	2.85		3.15	V
Zener operating resistance	RZ	IZ = 5 mA			120	Ω
Reverse current	IR	VR = 1 V			50	μA
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		-2.0		mV/°C

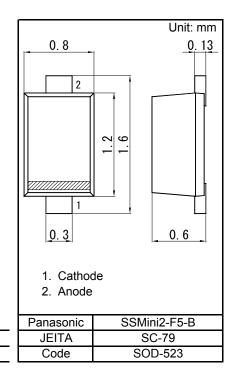
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

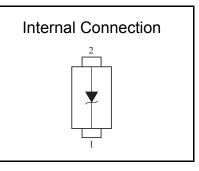
2. Absolute frequency of input and output is 5 MHz.

3. *1 The temperature must be controlled 25 $^{\circ}\text{C}$ for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25 $^\circ$ C).

*2	VZ guaranted 20 ms after current flow	Rank classification	l					
*3	Tj = 25 °C to 150 °C	Code	Code M Rank M		0			
		Rank			No-rank			
		VZ	2.93	to	3.08	2.85	to	3.15
		Marking symbol	3U		3J			

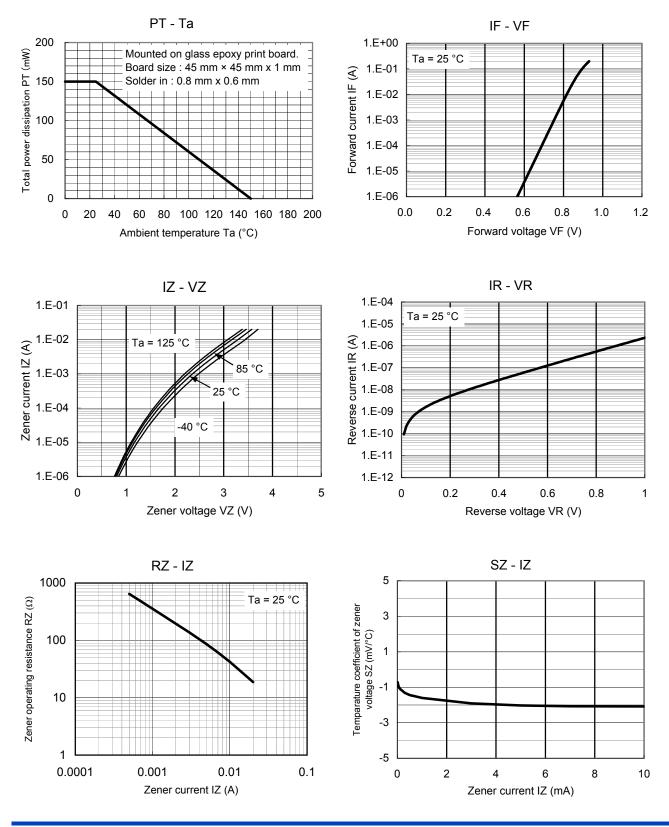






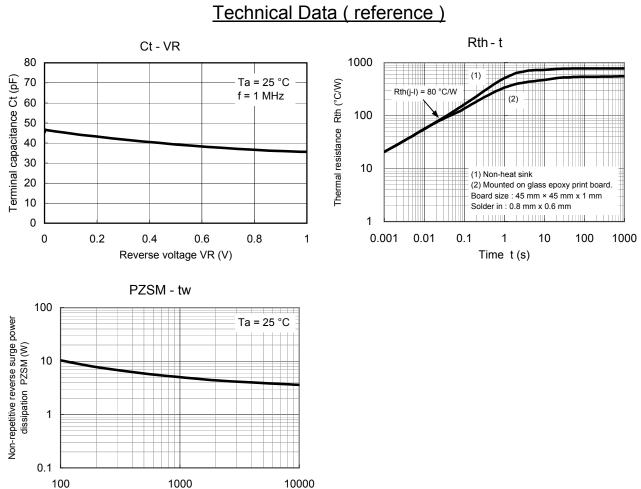
Zener Diode DZ2S030×0L

Technical Data (reference)



Established : 2009-11-09 Revised : 2013-07-16 **Panasonic**

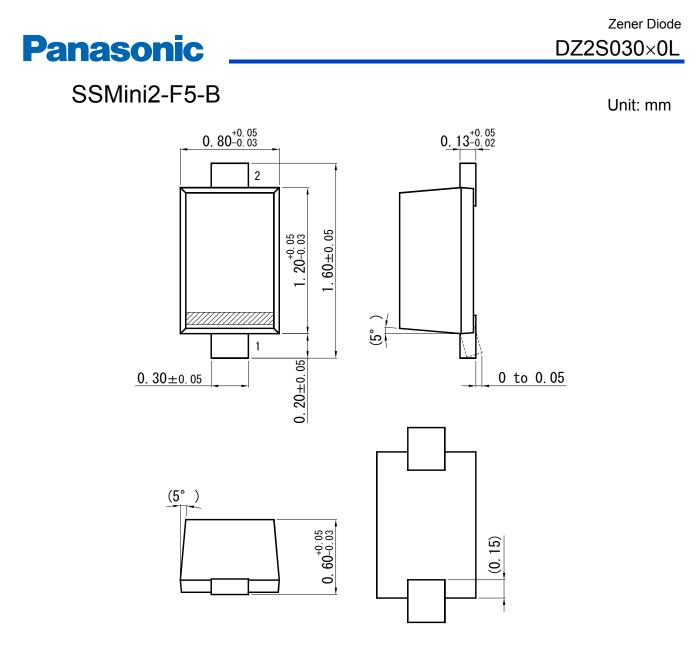
Zener Diode DZ2S030×0L



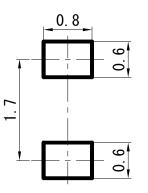
Pulse width tw (µs)

ata (reference)

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Land Pattern (Reference) (Unit: mm)



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